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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Bily WANG

Art unit: 2827 ✓

Serial No. 09/731,223 ✓

Examiner: MITCHELL, James M.

Filed: Dec.7, 2000

For: FOCUSING CUP ON A FOLDED FRAME FOR SURFACE MOUNT OPTOELECTRONIC
SSEMICONDUCTOR PACKAGE

AMENDMENT (marked-up version)

Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Sir:

In response to USPTO communication dated June 3, 2003, please amend the application as follows:

IN THE CLAIMS:

Please rewrite claim 1 as follows:

1 (once amended) A method of fabricating a surface mount semiconductor device package with a focusing cup, comprising the steps of:

preforming folded substrateless metal frames, each having a top surface for contacting an electrode of a semiconductor device and bottom surface serving as a contact for surface mounting to a motherboard, and

casting glue over said metal frames to form a cup over said top surface for focusing light emitted from said semiconductor device without covering the area for contacting said electrode and to adhere to said top surface as a unitary structure.

2. (once amended) [A] The method of fabricating a surface mount semiconductor device package as described in claim 1, wherein said folded substrateless metal frames are folded inward.

3. (once amended) [A] The method of surface mount semiconductor device package as described in claim 1, wherein said folded substrateless metal frames are folded outward .

4. (once amended) [A] The method of fabricating a surface mount semiconductor device package as described in claim 1, wherein said semiconductor device is a diode.

5. (once amended) [A] The method of fabricating a surface mount semiconductor device package as described in claim 1, wherein said cup is contoured to focus said light.